



The 23rd International Conference on Electrical Contacts

Together with IS-EMD2006

6-9 June 2006

Sendai International Center

Call for Papers



ICEC2006/Sendai

JAPAN

ICEC2006/Sendai

The 23rd International Conference on Electrical Contacts will be held June 6-9, 2006 at Sendai International Center, Sendai, Japan.

The first ICEC was organized by **Dr. Ragnar Holm** and **Prof. R. E. Armington**, and held in Main University, 1961. The ICEC was held in Japan twice.

The purpose of the ICEC2006/Sendai is to provide a forum for presenting and discussing the latest development and problems in the field of Electrical Contacts and the related area, and to promote an exchange of science and technical knowledge of specialists from all over the world.

The ICEC has greatly contributed for the development of this field and the promotion of international friendship.

TECHNICAL AREAS AND TOPICS

Basic Phenomena and Fundamentals

Static Contacts

- contact resistance
- fretting corrosion

Make-Break Contacts

- arc phenomena
- arc interruption
- erosion
- welding

Sliding Contacts

- lubrication
- friction
- wear

Materials

- metals and alloys
- plating
- conductive polymers

adhesives
 lead free solder
 new materials
Testing and Measurement
 lifetime test
 reliability
 methodology Evaluation
 modeling
 simulation
Electromechanical and Connection Devices
 switches
 circuit breakers (air and vacuum)
 permanent contacts
 connectors
 relays
 reed switches and reed relays
 micro-motors
 optical connectors and devices
Micro-Electromechanical Devices
 micro-switches
 nano-probes
 micro-welding
Interconnection
 communications
 broadband signal transmission
 degradation effects
 electromagnetic compatibility
Applications
 automotive electrical/electronic components
 communications
 power
 instrumentation
 sensors
New Areas

IMPORTANT DATES

Abstract Deadline	November 15, 2005
Notification of Acceptance	January 31, 2006
Completed Paper Deadline	March 15, 2006
Conference Begins	June 6, 2006

CONFERENCE

Official language English only
 Registration fee 50,000 Yen
 (Advanced registration fee)
 (Discount fee for students)

CONFERENCE OFFICE ADDRESS

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 Homepage: <http://www.ieice.org/icec2006/>

SPONSORSHIP(planned)

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 The Institute of Electronics, Information and Communication Engineers, Electronics Society (**IEICE-ES**)
 Cosponsored by;
 The Research and Engineering Society for Electromechanical Components and Contact Technology in Japan (**RES-ECCT**)
 et. al.

ABSTRACT SUBMISSION

Prospective authors should submit an abstract (200 words maximum) in English, in **word or pdf format** to the Program Committee (sawa@sd.keio.ac.jp), **before November 15, 2005**. The abstract must include: title, all authors, affiliation(s), author's postal and elec-

tronic addresses, telephone and FAX numbers, and other author's information as paper submission form. Authors will be notified concerning acceptance of abstracts by January 31, 2006. Papers will not be reviewed if they do not include complete contact information.

Selected papers will be published on a special issue of IEICE-ES Transactions after the review process of IEICE.

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